4.8mm BI-LEVEL LED INDICATOR

Part Number: WP73EB/2IDA High E

High Efficiency Red

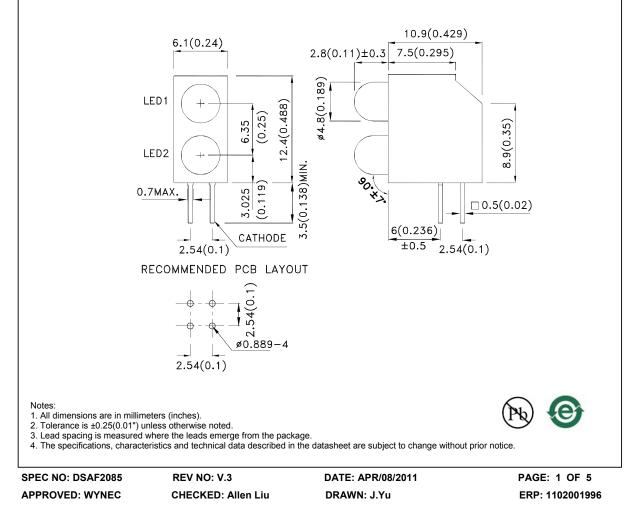
Features

- Pre-trimmed leads for pc board mounting.
- Colors can be mixed in a single housing.
- Black case enhances contrast ratio.
- Wide viewing angle.
- High reliability life measured in years.
- Housing UL rating:94V-0.
- Housing material: type 66 nylon.
- RoHS compliant.

Description

The High Efficiency Red source color devices are made with Gallium Arsenide Phosphide on Gallium Phosphide Orange Light Emitting Diode.

Package Dimensions



Selection Guide									
Part No.	Dice	Lens Type	lv (mcd) [2] @ 10mA		Viewing Angle [1]				
			Min.	Тур.	201/2				
WP73EB/2IDA	High Efficiency Red (GaAsP/GaP)	Red Diffused	15	40	60°				

Notes:

01/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.
Luminous intensity/ luminous Flux: +/-15%.

Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	High Efficiency Red	627		nm	l⊧=20mA
λD [1]	Dominant Wavelength	High Efficiency Red	625		nm	l⊧=20mA
Δλ1/2	Spectral Line Half-width	High Efficiency Red	45		nm	l⊧=20mA
С	Capacitance	High Efficiency Red	15		pF	VF=0V;f=1MHz
VF [2]	Forward Voltage	High Efficiency Red	2	2.5	V	l⊧=20mA
IR	Reverse Current	High Efficiency Red		10	uA	VR = 5V

Notes:

1.Wavelength: +/-1nm. 2. Forward Voltage: +/-0.1V.

Absolute Maximum Ratings at TA=25°C

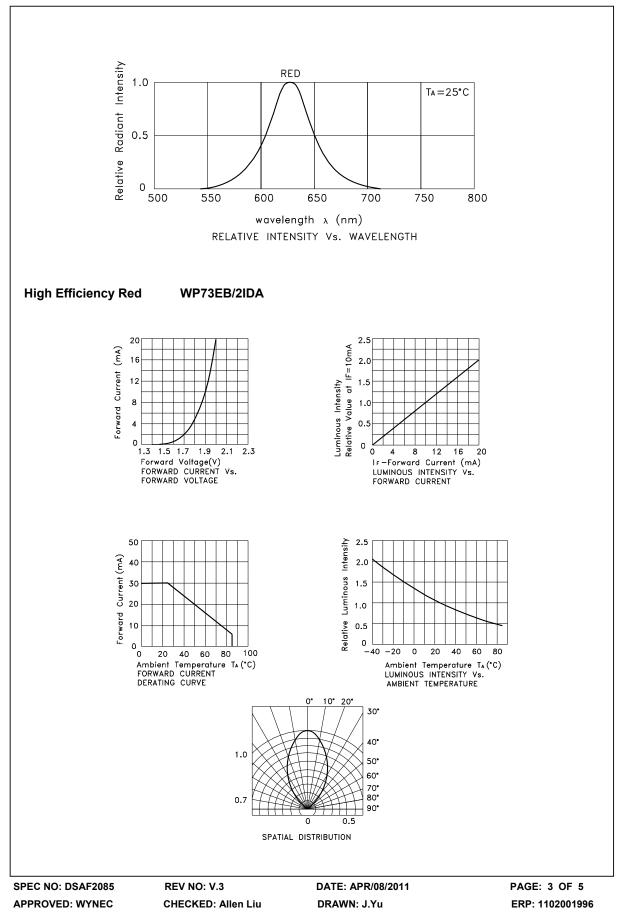
Parameter	High Efficiency Red			
Power dissipation	er dissipation 75			
DC Forward Current	30	mA		
Peak Forward Current [1]	160	mA		
Reverse Voltage	5	V		
perating/Storage Temperature -40°C To +85°C				
Lead Solder Temperature [2] 260°C For 3 Seconds				
Lead Solder Temperature [3]	260°C For 5 Seconds			
Notes: 1. 1/10 Duty Cycle, 0.1ms Pulse Width.				

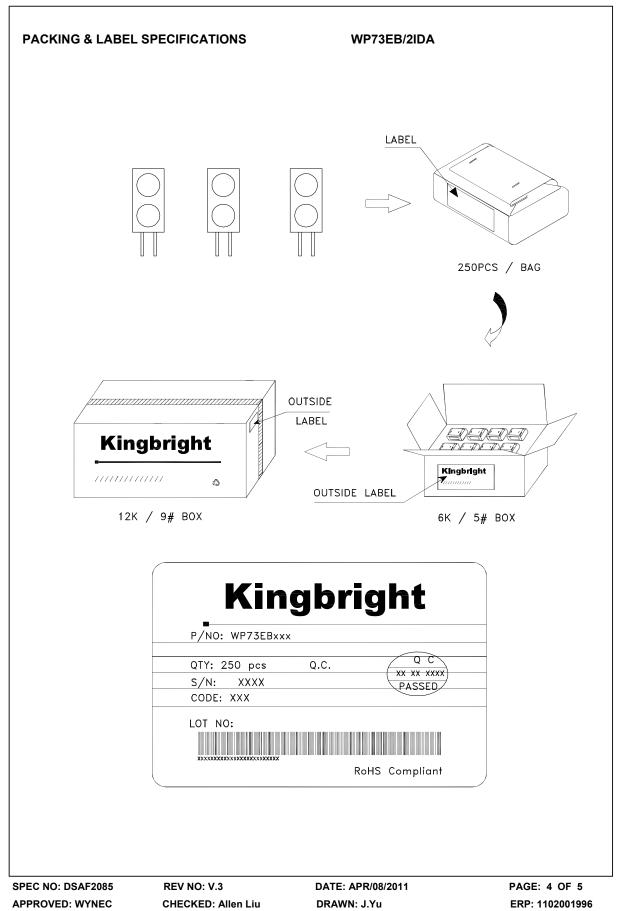
2. 2mm below package base.
3. 5mm below package base.

SPEC NO: DSAF2085 APPROVED: WYNEC

REV NO: V.3 CHECKED: Allen Liu DATE: APR/08/2011 DRAWN: J.Yu

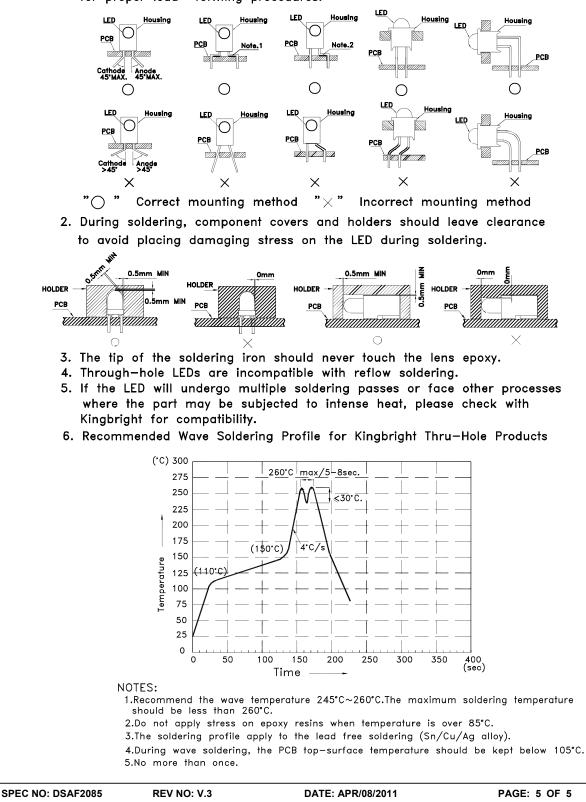
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PRECAUTIONS

1. The lead pitch of the LED must match the pitch of the mounting holes on the PCB during component placement. Lead-forming may be required to insure the lead pitch matches the hole pitch. Refer to the figure below for proper lead forming procedures.



DRAWN: J.Yu

ERP: 1102001996

APPROVED: WYNEC

CHECKED: Allen Liu